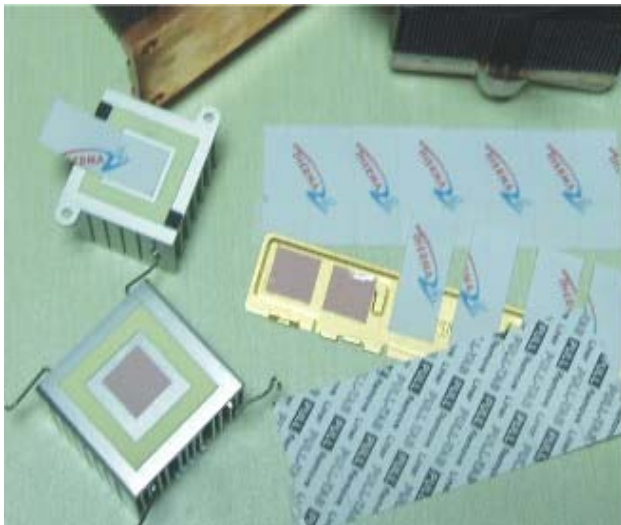


TIC™800P Series is low melting point thermal interface material. At 50 °C, TIC™800P series begins to soften and flow, filling the microscopic irregularities of both the thermal solution and the integrated circuit package surface, thereby reducing thermal resistance. TIC™800P series is a flexible solid at room temperature and freestanding without reinforcing components that reduce thermal performance.

TIC™800P Series shows no thermal performance degradation after 1,000 hours @ 130 °C, or after 500 cycles, from -25 °C to 125 °C. The material softens and does not fully change state resulting in minimal migration (pump out) at operating temperatures.



低熔點導熱界面材料

TIC™800P系列是一種高性能低熔點導熱界面材料。在溫度50°C，TIC™800P開始軟化並流動，填充散熱片和積體電路板的接觸介面上細微不規則間隙，以達到減小熱阻的目的。TIC™800P系列在室溫下呈可彎曲固態，無需增強材料而獨立使用，免除了增強材料對熱傳導性能的影響。

TIC™800P系列在溫度130°C下持續1000小時，或經歷-25°C到125°C的反覆循環測試，其導熱性能仍不會減退。在工作溫度下，其中相變材料軟化的同時又不會完全液化或溢出。

For Lowest Thermal Resistance :

- › **0.021°C-in² /W** thermal resistance
- › Naturally tacky at room temperature, no adhesive required
- › No heat sink preheating required

Applications Include:

- › High Frequency Microprocessors
- › Notebook and Desktop PCs
- › Computer Servers
- › Memory Modules
- › Cache Chips
- › IGBTs

最小熱阻系列:

- › **0.021°C-in² /W** 熱阻
- › 室溫下具有天然黏性, 無需黏合劑
- › 散熱器無需預熱

適用於:

- › 高頻率微處理器
- › 筆記本和桌上型電腦
- › 電腦伺服器
- › 記憶體模組
- › 快取記憶體晶片
- › IGBTs

Gap Fillers | Phase Change Materials | Thermally Conductive Insulators | Thermally Conductive PCB Materials | Greases | Thermally Conductive Adhesive Tapes



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以上資料與說明相信是可靠的但不作為法律的解釋或保證。用戶須進行充分的測試與確認上述訊息適合用戶所提出任何特殊的产品与应用。

Typical Properties of TIC™800P Series

TIC™800P 系列特性表

Product Name (產品名稱)	TIC™803P	TIC™805P	TIC™808P	TIC™810P	Test Method (測試標準)
Color (顏色)	Pink (粉紅)	Pink (粉紅)	Pink (粉紅)	Pink (粉紅)	Visual (目視)
Thickness (厚度)	0.003" (0.076mm)	0.005" (0.126mm)	0.008" (0.203mm)	0.010" (0.254mm)	
Thickness Tolerance (厚度公差)	±0.0006" (±0.016mm)	±0.0008" (±0.019mm)	±0.0008" (±0.019mm)	±0.0012" (±0.030mm)	
Density (密度)	2.2g/cc				Helium Pycnometer
Temperature range (工作溫度)	-25°C ~ 125°C				
Phase Change Softening Temperature (相變溫度)	50°C ~ 60°C				
"Burn In" Temperature (定型溫度)	70°C for 5 minutes				
Thermal Conductivity (熱傳導率)	0.95 W/mK				ASTM D5470 (modified)
Thermal Impedance (熱阻抗) @ 50 psi(345 KPa)	0.021°C-in²/W	0.024°C-in²/W	0.053°C-in²/W	0.080°C-in²/W	ASTM D5470 (modified)
	0.14°C-cm²/W	0.15°C-cm²/W	0.34°C-cm²/W	0.52°C-cm²/W	

Standard Thicknesses(標準厚度):

0.003"(0.076mm) 0.005"(0.127mm) 0.008"(0.203mm) 0.010"(0.254mm)

Consult the factory alternate thickness.(如需不同厚度請與本公司聯繫。)

Standard Sizes(標準尺寸):

10" x 16"(254mm x 406mm) 16" X 400' (406mm X 121.92M)

TIC™800 series are supplied with a white release paper and a bottom liner. TIC™800 series is available in kiss cut an extended pull tab liner or individual die cut shapes.

(TIC™800 系列片料供應時附有白色離型紙及底襯墊，模切半斷加工可提供拉手,也可提供模切成單個形狀型試提供。)

Peressure Sensitive Adhesive(壓敏黏合劑):

Peressure Sensitive Adhesive is not applicable for TIC™800 series products.(壓敏黏合劑不適用於TIC™800 系列產品。)

Reinforcement(補強材料):

No reinforcement is necessary.(無需補強材料。)